

L Number	Hits	Search Text	DB	Time stamp
-	8	ohkura.in. and ryoichi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 14:19
-	1160	ono.in. and yuji.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 14:19
-	74	(ono.in. and yuji.in.) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 14:20
-	45	(ono.in. and yuji.in.) and (semiconductor or wafer or substrate).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 14:22
-	6289	yamaguchi.in. and hiroshi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 14:22
-	303	(yamaguchi.in. and hiroshi.in.) and (semiconductor or wafer or substrate).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 14:25
-	10	((yamaguchi.in. and hiroshi.in.) and (semiconductor or wafer or substrate).ti.) and (ohkura or ono or takaishi or kamikochi).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 14:27
-	1787	takaishi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 14:25
-	171	takaishi.in. and (semiconductor or wafer or substrate).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 14:25
-	171	(takaishi.in. and (semiconductor or wafer or substrate).ti.) and (ohkura or ono or takaishi or kamikochi).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 14:25
-	2	((takaishi.in. and (semiconductor or wafer or substrate).ti.) and (ohkura or ono or takaishi or kamikochi).in.) and booth	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 15:24
-	3249	134/61-83.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 15:47

-	15	134/61-83.ccls. and (robot adj arm)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 15:48
-	14	134/61-83.ccls. and booth	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 15:46
-	1854	134/902.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 16:12
-	64	134/902.ccls. and (robot adj arm)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 16:12
-	26	(134/902.ccls. and (robot adj arm)) and (load\$3 and unload\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 16:13
-	2914	134/61,66,78,200,902.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 16:12
-	71	134/61,66,78,200,902.ccls. and (robot adj arm)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 16:12
-	26	(134/61,66,78,200,902.ccls. and (robot adj arm)) and (load\$3 and unload\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/26 16:13